









PRODUCT DATASHEET



- ► DC Input Photo Coupler
- ► SMD6 Low Profile
- ► Random-Phase TRIAC

TD301X(SL)(T1)-GV(W)





TD301X(SL)(W) Series

DESCRIPTION:





The TD301X(SL)(W) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo TRIAC in a plastic DIP6 package with SMD6 Low Profile lead forming option.

With the robust coplanar double mold structure, TD301X(SL) (W) series provide the most stable isolation feature.

APPLICATIONS:

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

FEATURES:

- High isolation 5000Vrms
- DC input with random-phase photo TRIAC output
- Operating temperature range -40°C to +100°C
- **REACH & RoHS compliance**
- MSL class 1
- Regulatory Approvals:
 - UL UL1577
 - VDE EN60747-5-5 (VDE0884-5)
 - CQC GB4943.1, GB8898
 - cUL CSA Component Acceptance Service Notice 5A

Packing: 1000pcs/reel







Release Date: 26 June 2025 Version: A01



NAMING & ORDERING INFORMATION:

Naming Information:

TD301 X (SL) (T1) - G V (W)				
TD301X	Part Number			
×	Selection: LED Trigger Current (X=0~2)			
SL	Lead Form Option: SMD6 Low Profile			
T1	Selection: Tape and Reel Option (T1(default)/T2)			
G	Green Option			
V	VDE Option			
W	White Package			

Ordering Information:

TD301<u>X</u>(SL)(T1)-GV(W)

 \underline{X} = Selection: LED Trigger Current (X=0~2)

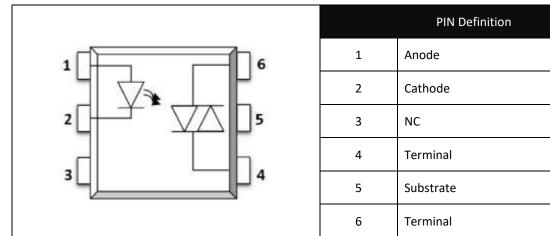
Part Number	Symbol	Values			Unit	Test Condition
	Symbol	Min.	Тур.	Max.	Unit	rest Condition
TD3010(SL)(T1)-GV(W)	l _{FT}			15		100 1
TD3011(SL)(T1)-GV(W)				10	mA	I™=100mA Terminal Voltage=3V
TD3012(SL)(T1)-GV(W)				5		

Version No.	Original Release Date
Rev: A01	21/06/2021

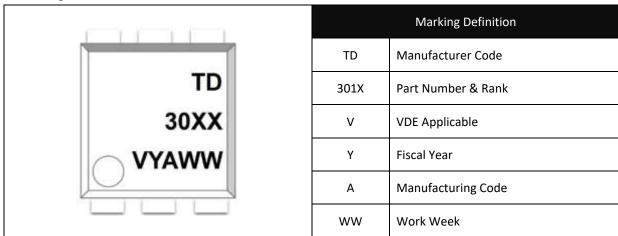


SCHEMATIC DIAGRAM & MARKING:

Schematic Diagram:



Marking Information:



Labelling Information:



This product is manufactured, tested, and packed by



for more details, please visit www.tdled.com



ABSOLUTE CHARACTERISTICS:

Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit
	INPUT		
Forward Current	lF	60	mA
Reverse Voltage	V _R	6	V
Junction Temperature	Tj	125	°C
Input Power Dissipation	Pı	100	mW
	OUTPUT		
Off-State Output Terminal Voltage	V _{DRM}	250	V
Peak Repetitive Surge Current PW=100µs, 120pps	Ітѕм	1	А
On-State RMS Current	I _{T(RMS)}	100	mA
Junction Temperature	Tj	125	°C
Output Power Dissipation	Po	300	mW
	COMMON		
Total Power Dissipation	P _{tot}	400	mW
Isolation Voltage	V _{iso}	5000 *1	Vrms
Operating Temperature	T _{opr}	-40~+100	°C
Storage Temperature	T _{stg}	-55~+125	°C
Soldering Temperature	T _{sol}	260 *²	°C

^{*1.} AC for 1 minute, R.H.= $40^{\circ}60\%$.

^{*2.} For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

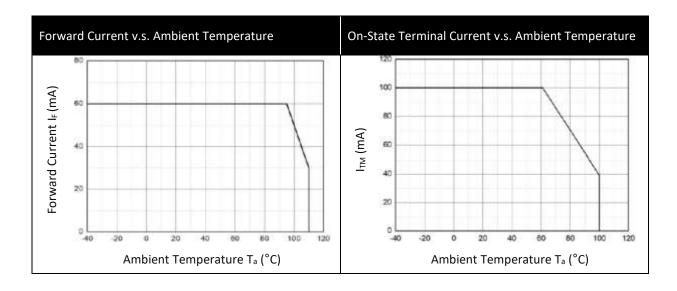
Electrical Optical Characteristics at T_a=25°C:

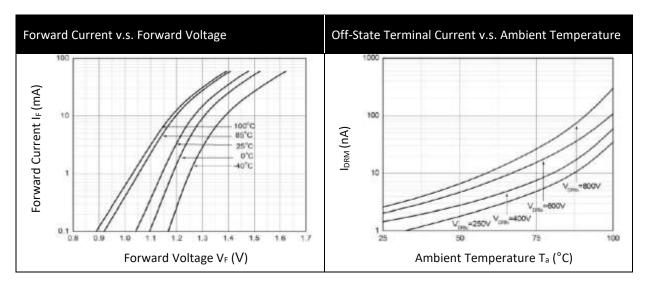
Parameter		Symphol	Symbol Values			Lloit	Tost Condition
		Symbol	Min.	Тур.	Max.	Unit	Test Condition
	INPUT						
Forward Voltage		V _F		1.24	1.4	V	I _F =10mA
Reverse Current		I _R			10	μΑ	V _R =6V
Input Capacitance		Cin		8.5	250	pF	V=0, f=1kHz
			OUTPU	JT			
Peak Off-State Currer Either Direction	nt	I _{DRM}			100 *1	nA	V _{DRM} =Rated V _{DRM} I _F =0
Peak On-State Voltag	e	V _{TM}		1.58	2.5	V	I _{TM} =100mA
Critical Rate of Rise o Voltage	f Off-State	dV/dt	1000			V/µs	V _{PEAK} =400V I _F =0
	TRANSFER CHARACTERISTICS						
LED Trigger Current	TD3010				15		100
	TD3011	I _{FT}			10	mA	I _™ =100mA Terminal
	TD3012				5		Voltage=3V
Holding Current		lн		257		μΑ	
Isolation Resistance		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.8		pF	V=0, f=1MHz

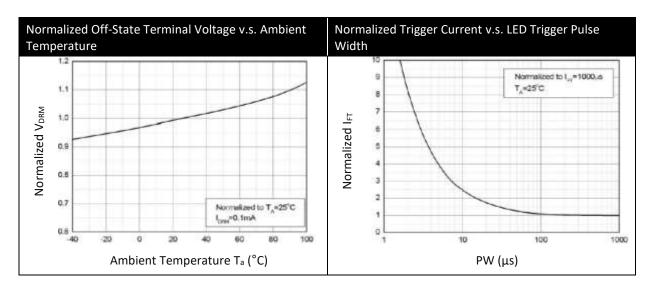
 $^{^{*}}$ 1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

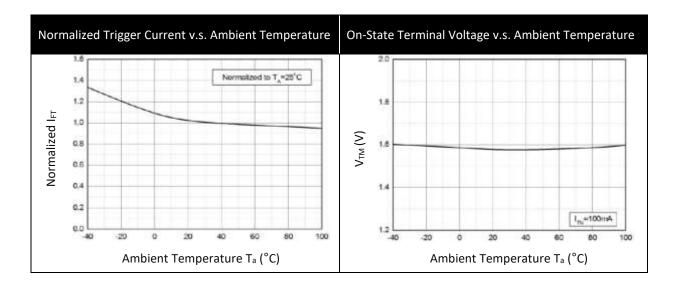


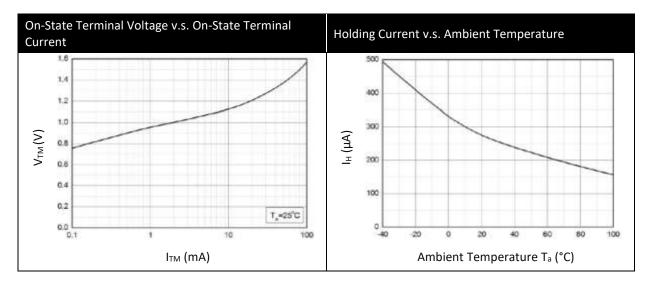


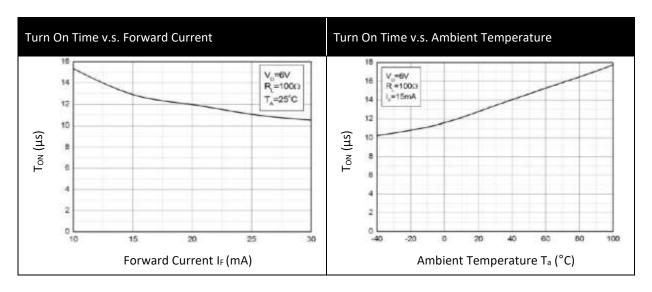




CHARACTERISTIC CURVES:



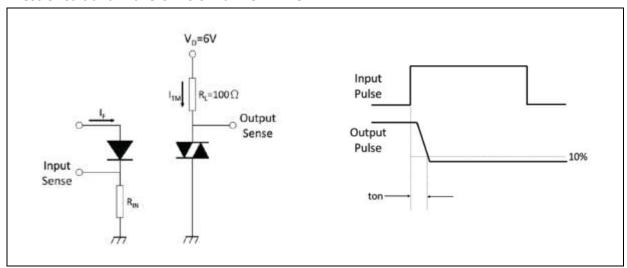




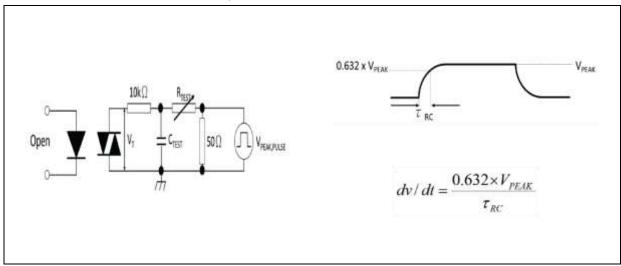


TEST CIRCUIT:

Test Circuit and Waveforms of Turn On Time:



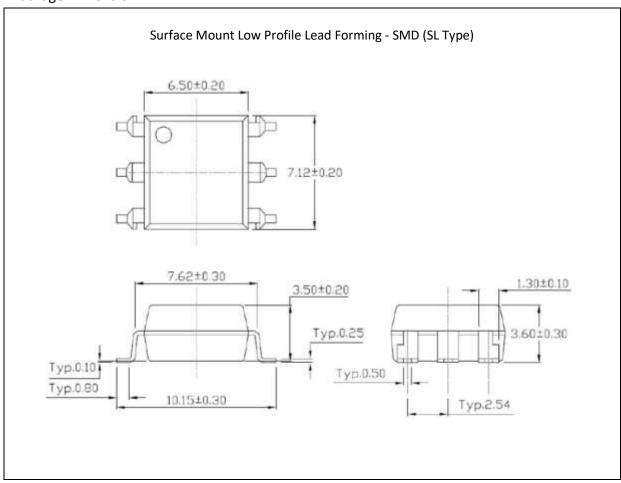
Test Circuit and Waveforms of dV/dt:





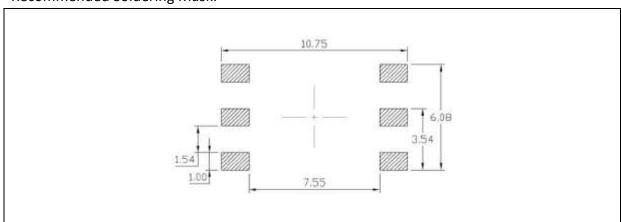
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

Recommended Soldering Mask:

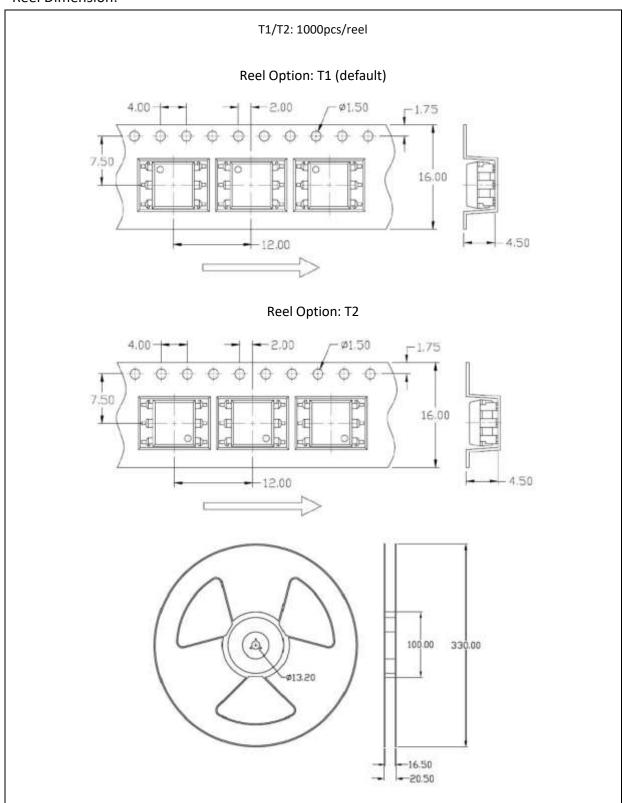


1. Dimensions are in millimetre (mm).



PACKING SPECIFICATION:

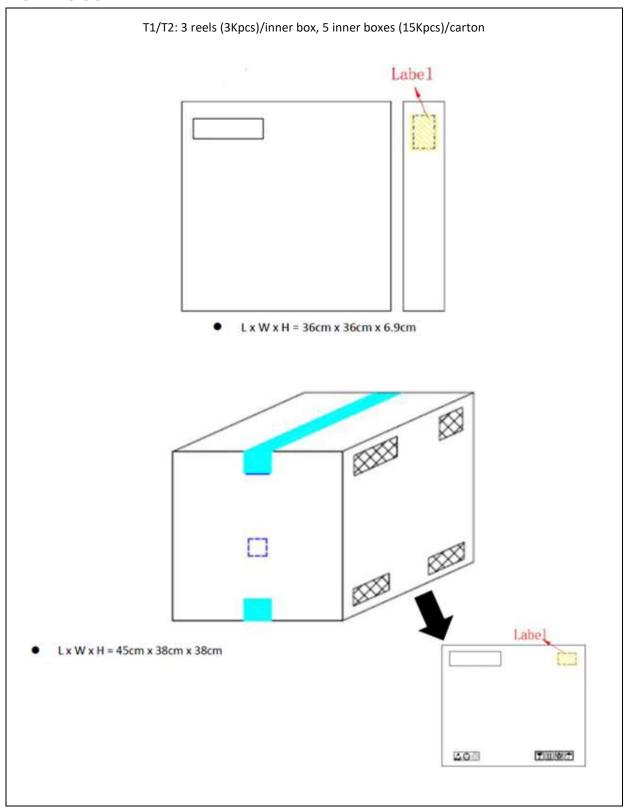
Reel Dimension:





PACKING SPECIFICATION:

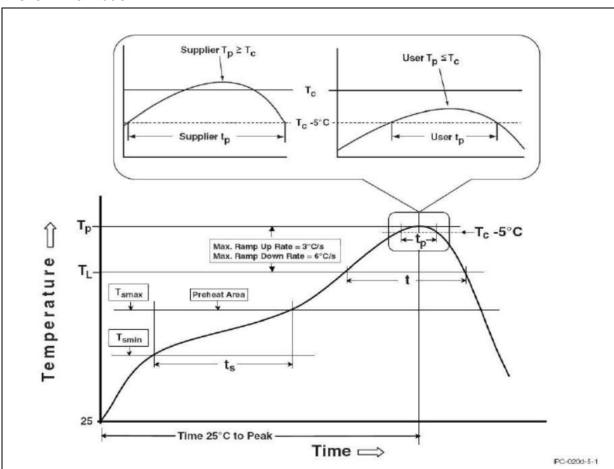
Box Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

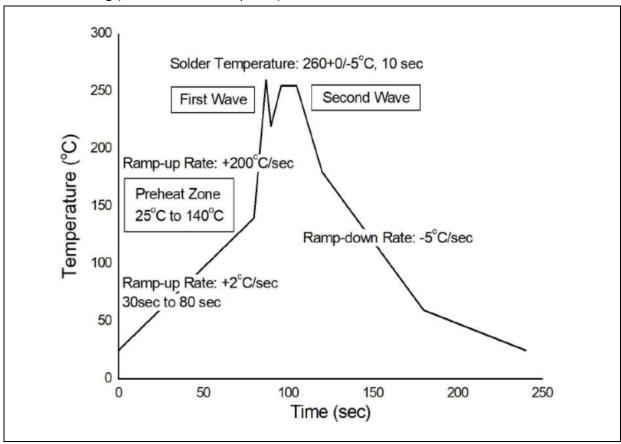


Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100°C	150°C
Temperature Max. (T _{smax})	150°C	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.